



# VOIDLESS HERMETICALLY SEALED SURFACE MOUNT STANDARD RECOVERY GLASS RECTIFIERS

Qualified to MIL-PRF-19500/420

<u>Qualified Levels:</u> JAN, JANTX, JANTXV and JANS

#### DESCRIPTION

This "standard recovery" surface mount rectifier diode series is military qualified and is ideal for high-reliability applications where a failure cannot be tolerated. These industry-recognized 5.0 amp rated rectifiers for working peak reverse voltages from 200 to 1000 volts are hermetically sealed with voidless-glass construction using an internal "Category 1" metallurgical bond. These devices are also available in axial-leaded packages for thru-hole mounting. Microsemi also offers numerous other rectifier products to meet higher and lower current ratings with various recovery time speeds.

Important: For the latest information, visit our website http://www.microsemi.com.

#### **FEATURES**

- Surface mount equivalent of JEDEC registered 1N5550 thru 1N5554 series.
- Voidless hermetically sealed glass package.
- Extremely robust construction.
- Quadruple-layer passivation.
- Internal "Category 1" metallurgical bonds.
- JAN, JANTX, JANTXV and JANS qualified versions available per MIL-PRF-19500/420.
- RoHS compliant versions available (commercial grade only).

#### **APPLICATIONS / BENEFITS**

- Standard recovery 5 amp 200 to 1000 volts rectifiers series.
- · Military and other high-reliability applications.
- General rectifier applications including bridges, half-bridges, catch diodes, etc.
- High forward surge current capability.
- Low thermal resistance.
- Controlled avalanche with peak reverse power capability.
- Extremely robust construction.
- Inherently radiation hard as described in Microsemi "MicroNote 050".

#### MAXIMUM RATINGS @ T<sub>A</sub> = 25 °C unless otherwise noted.

Parameters/Test Conditions		Symbol	Value	Unit
Junction and Storage Temperature		$T_J$ and $T_{STG}$	-65 to +175	°C
Thermal Resistance Junction-to-End Cap		R <sub>OJEC</sub>	6.5	°C/W
Thermal Impedance @ 10 ms heating time (1)		$Z_{\Theta JX}$	1.5	°C/W
Maximum Forward Surge Current (8.3 ms half sine)		I <sub>FSM</sub>	100	Α
Average Rectified Forward Current (2)	@ $T_{EC} = 130  ^{\circ}C$	I <sub>O(L)</sub>	5	Α
Average Rectified Forward Current (3)	@ $T_A = 55$ °C	I <sub>O2</sub> (2)	3	Α
	$@ T_A = 100  {}^{\circ}C$	I <sub>O3</sub> <sup>(4)</sup>	2	Α
Working Peak Reverse Voltage	1N5550US	$V_{RWM}$	200	V
	1N5551US		400	
	1N5552US		600	
	1N5553US		800	
	1N5554US		1000	
Solder Temperature @ 10 s		T <sub>SP</sub>	260	оС

See notes on next page.

"B" SQ-MELF (D-5B)
Package

#### Also available in:

"B" Package (axial-leaded) 1N5550 – 1N5554

#### MSC – Lawrence 6 Lake Street,

Lawrence, MA 01841 Tel: 1-800-446-1158 or (978) 620-2600 Fax: (978) 689-0803

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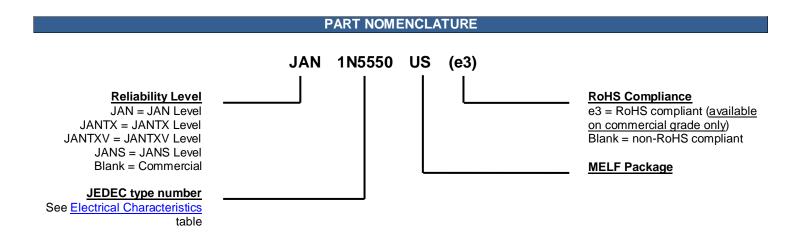


#### **MAXIMUM RATINGS**

- Notes: 1. Derate linearly at 66.6 mA/°C above T<sub>EC</sub> = 100 °C. An I<sub>O</sub> of up to 6 Amps is allowable provided that appropriate heat sinking or forced air cooling maintains the junction temperature at or below +200 °C.
  - 2. Derate linearly at 22.2 mA/°C from +55 °C to +100 °C.
  - These I<sub>O</sub> ratings are for a thermally (PC boards or other) mounting methods where the lead or end-cap temperatures cannot be maintained and where thermal resistance from mounting point to ambient is still sufficiently controlled where T<sub>J(MAX)</sub> does not exceed 175 °C. This equates to R<sub>B,IX</sub> ≤ 47 °C/W.
  - 4. Derate linearly at 26.7 mA/°C above  $T_A$ = +100 °C to +175 °C ambient.

#### **MECHANICAL and PACKAGING**

- CASE: Hermetically sealed voidless hard glass with tungsten slugs.
- TERMINALS: End caps are copper with tin/lead (Sn/Pb) finish. RoHS compliant matte-tin is available for commercial only.
- MARKING: Cathode band only.
- POLARITY: Cathode indicated by band.
- TAPE & REEL option: Standard per EIA-481-B. Consult factory for quantities.
- WEIGHT: 539 milligrams.
- See <u>Package Dimensions</u> and recommended <u>Pad Layout</u> on last page.



SYMBOLS & DEFINITIONS		
Symbol	Definition	
$V_{BR}$	Minimum Breakdown Voltage: The minimum voltage the device will exhibit at a specified current.	
$V_{RWM}$	Working Peak Reverse Voltage: The maximum peak voltage that can be applied over the operating temperature range excluding all transient voltages (ref JESD282-B).	
Io	Average Rectified Output Current: The Output Current averaged over a full cycle with a 50 Hz or 60 Hz sine-wave input and a 180 degree conduction angle.	
V <sub>F</sub>	Maximum Forward Voltage: The maximum forward voltage the device will exhibit at a specified current.	
I <sub>R</sub>	Maximum Reverse Current: The maximum reverse (leakage) current that will flow at the specified voltage and temperature.	
t <sub>rr</sub>	Reverse Recovery Time: The time interval between the instant the current passes through zero when changing from the forward direction to the reverse direction and a specified decay point after a peak reverse current occurs.	



## **ELECTRICAL CHARACTERISTICS** @ $T_A = 25$ °C unless otherwise noted.

ТҮРЕ	MINIMUM BREAKDOWN VOLTAGE V <sub>BR</sub>	FORWARD VOLTAGE V <sub>F</sub> @ 9 A (pk)		MAXIMUM REVERSE CURRENT I <sub>R</sub> @ V <sub>RWM</sub>	REVERSE RECOVERY
	I <sub>R</sub> @ 50 μA Volts	MIN. Volts	MAX. Volts	μA	(Note 1) μs
1N5550US	220	0.6 V (pk)	1.2 V (pk)	1.0	2.0
1N5551US	440	0.6 V (pk)	1.2 V (pk)	1.0	2.0
1N5552US	660	0.6 V (pk)	1.2 V (pk)	1.0	2.0
1N5553US	880	0.6 V (pk)	1.3 V (pk)	1.0	2.0
1N5554US	1100	0.6 V (pk)	1.3 V (pk)	1.0	2.0

NOTE 1:  $I_F = 0.5 \text{ A}$ ,  $I_{RM} = 1.0 \text{ A}$ ,  $I_{R(REC)} = .250 \text{ A}$ .



#### **GRAPHS**

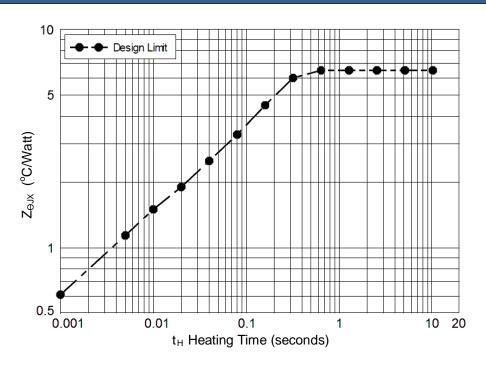


FIGURE 1

Maximum Thermal Impedance

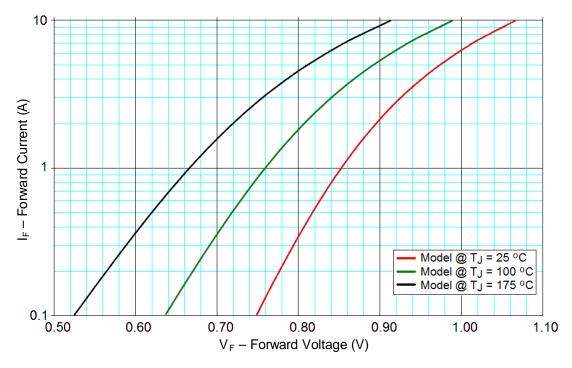
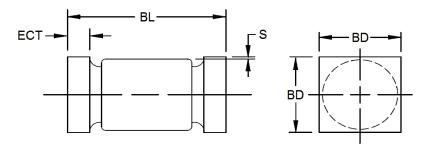


FIGURE 4

Typical Forward Voltage vs. Forward Current



#### **PACKAGE DIMENSIONS**

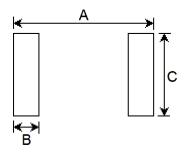


Ltr	Inch		Millimeters		
	MIN	MAX	MIN	MAX	
BL	.200	.275	5.08	6.99	
BD	.137	.186	3.48	4.72	
ECT	.019	.034	0.48	0.86	
s	.003		0.08		

#### **NOTES:**

- 1. Dimensions are in inches.
- 2. Millimeters are given for general information only.
- 3. Dimensions are pre-solder dip.
- 4. Minimum clearance of glass body to mounting surface on all orientations.
- 5. In accordance with ASME Y14.5M, diameters are equivalent to  $\Phi x$  symbology.
- 6. This package outline has also previously been identified as "D5B".

### **PAD LAYOUT**



Ltr	Inch	Millimeters
Α	0.288	7.32
В	0.070	1.78
С	0.155	3.94

Note: If mounting requires adhesive separate from the solder, an additional 0.080 inch diameter contact may be placed in the center between the pads as an optional spot for cement.

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ACGRB207-HF CLH03(TE16L,Q) ACGRC307-HF ACEFC304-HF NTE6356 NTE6359 NTE6002 NTE6023 NTE6039 NTE6077
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